10400 Eaton Place -Suite 312 FAIRFAX, VA Phone: (703) 385-5200 Fax: (703) 385-5080

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KEATING & BENNETT LLP



Examiner J. Gonzalez Christopher A. Bennett From: To: 703-872-9319 February 27, 2003 Date: Fax: Phone: 703-305-1563 Pages: 17 09/656,106 CG: Re: 36856.345

•Comments:

Examiner Gonzalez,

Please find attached the following documents for U.S. Application No. 09/656,106:

- 1. Amendment After Final Rejection;
- Petition for 2-month extension of time;
- 3. Credit card form in the amount of \$410.00;
- Notice of Appeal (2 copies); and
- Credit card form in the amount of \$320.00.

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FEB 2 7 2003

TECHNOLOGY CENTER 2800

Respectfully submitted

Christopher A. Bennett

KEATING & BENNETT, LLP

(Reg. No. 46,710)

RESPONSE UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE GROUP ART UNIT 2834

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being transmitted to Group Art Unit 2834, 703-872-9319, addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: February 27, 2003

Sonia V. McVean

PATENT 36856,345

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Masaya WAJIMA et al.

Serial No.: 09/656,106

Filed: September 6, 2000

Title: CHIP ELECTRONIC COMPONENT

AND MOUNTING STRUCTURE FOR

THE SAME

Art Unit: 2834

Examiner: J. Gonzalez

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AMENDMENT AFTER FINAL REJECTION

TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action dated October 23, 2002, the period for response to which has been extended to March 23, 2003, by the accompanying Petition for a TWO-month Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please REPLACE claim 14 with the following claim:

14. (Twice amended) A chip electronic component comprising:

03/17

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a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;

an electronic component element having electrodes and defining part of said body of the chip electronic component; and

a plurality of external electrodes arranged so as to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element:

wherein each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is arranged to have an almost uniform width from one longitudinal end to the other, and satisfy the relation L₁<L₃, where L₃ is the width of each portion of the external electrodes provided on the lower surface of said body of the chip electronic component, and L1 is the width of each portion of the external electrodes provided on the at least one side surface of said body of the chip electronic component, each of the widths L₁ and L₃ being defined as a dimension of the external electrodes measured in a longitudinal direction of the body of the chip electronic component.